

Abstract

After a trench 14 has been formed in a conductive foil 60, a circuit element is mounted on the conductive foil 60. The surface of the structure is covered with insulating resin 10 using the conductive foil 60 as a supporting board. After the structure has been turned upside down, this time, the conductive foil is polished using the insulating resin 10 as a supporting board so that it is separated into conductive paths 11. Therefore, a semiconductor device 13 in which the conductive paths 11 and the semiconductor chip 12 are supported by the insulating resin 10 can be realized with no supporting board. In addition, since the semiconductor chip 12 is thermally coupled with a conductive path 11A, heat generated in the semiconductor chip 12 can be radiated externally.